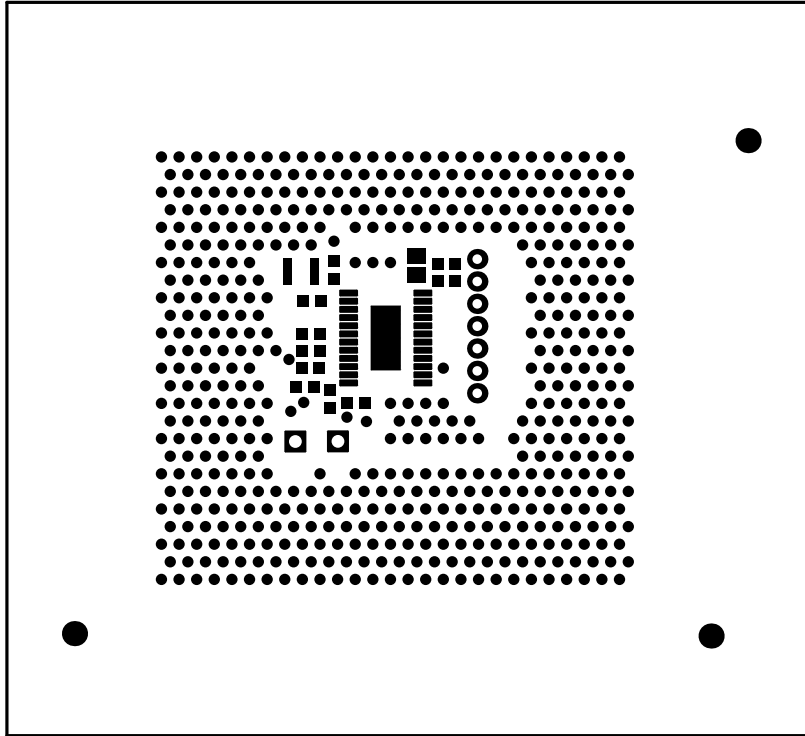
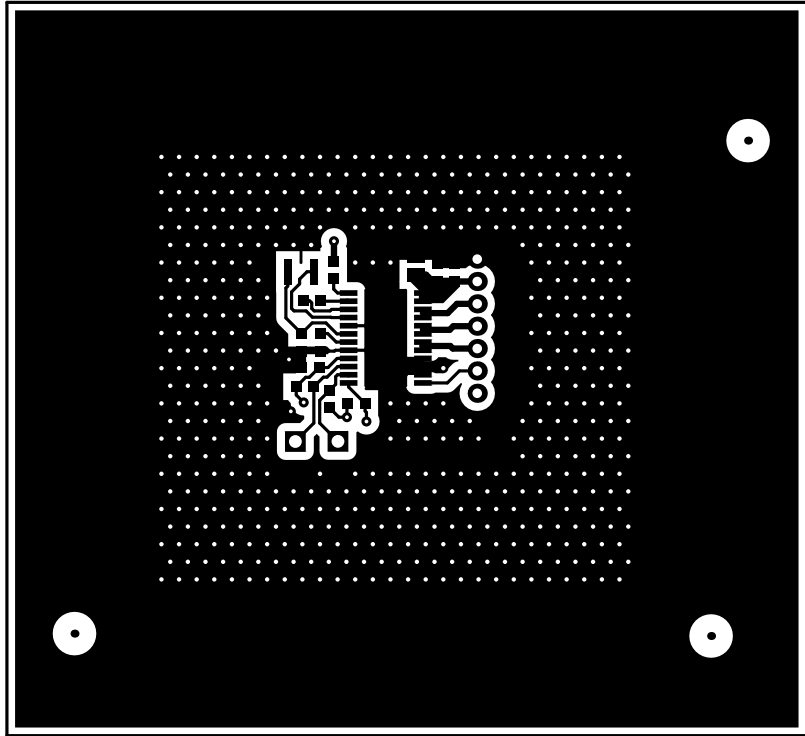


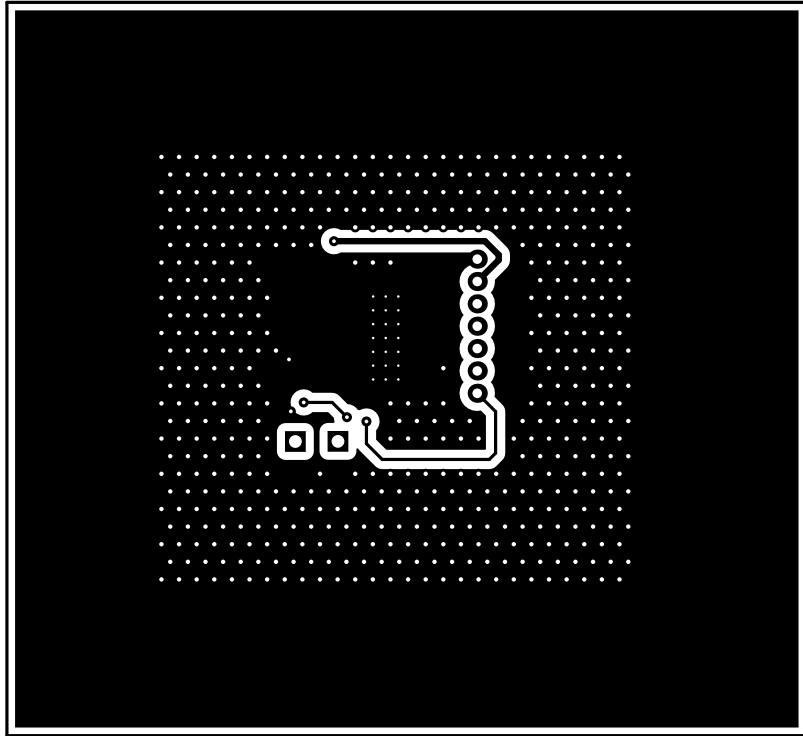
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01493	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01493		
PLOT NAME = Top Overlay	GENERATED : 10/23/2017 3:25:31 PM		TEXAS INSTRUMENTS



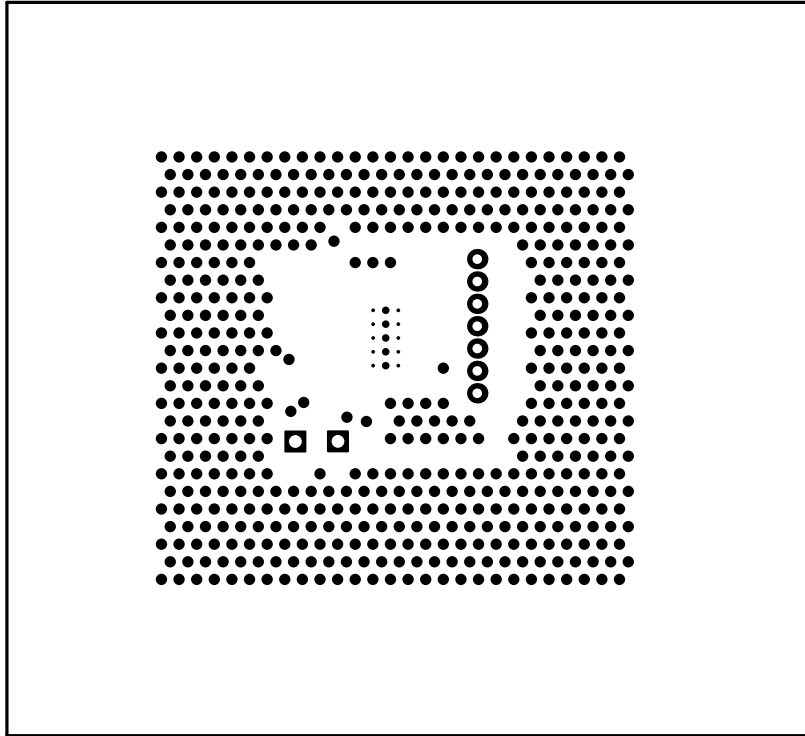
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01493	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01493		
PLOT NAME = Top Solder Mask	GENERATED : 10/23/2017 3:25:31 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01493	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01493		
PLOT NAME = Top Layer	GENERATED : 10/23/2017 3:25:31 PM		TEXAS INSTRUMENTS

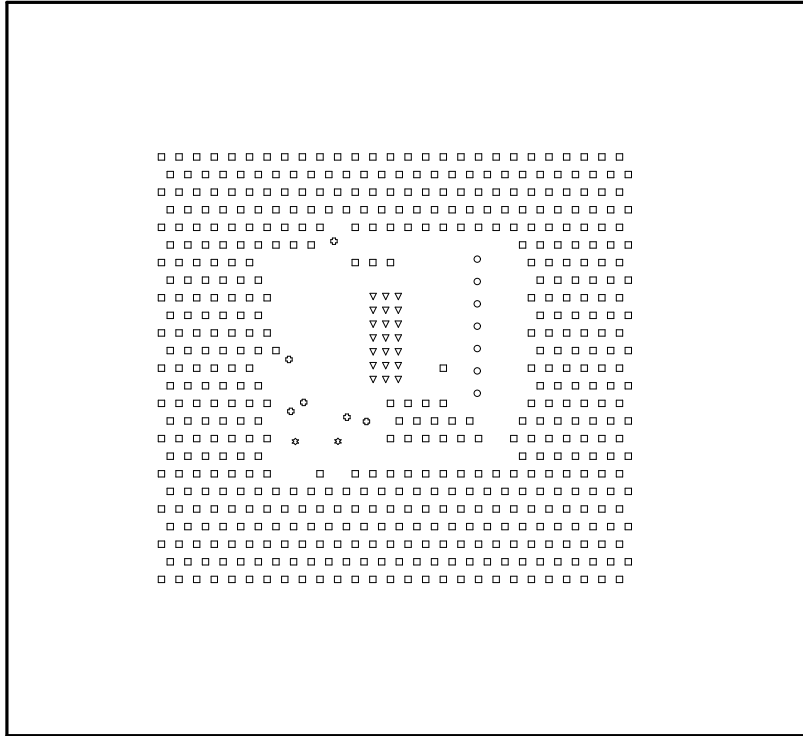


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01493	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01493		
PLOT NAME = Bottom Layer	GENERATED : 10/23/2017 3:25:31 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01493	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01493		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/23/2017 3:25:31 PM		TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	21	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	6	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
□	507	13.78mil (0.350mm)	PTH	Round	Top Layer - Bottom Layer	
○	7	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	2	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
	543 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01493	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01493		
PLOT NAME = Drill Drawing	GENERATED : 10/23/2017 3:25:31 PM		TEXAS INSTRUMENTS

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